

## Combined Declaration for Patent Application and Power of Attorney

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled SEMICONDUCTOR DEVICE, METHOD OF MANUFACTURING THE SAME, AND METHOD OF MANUFACTURING METAL COMPOUND THIN FILM the specification of which

(check one)	is attached hereto.		
<input checked="" type="checkbox"/>	was filed on	March 24, 2004	as International Application No.
PCT/JP2004/004060			
and (if applicable) was amended on:			

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information, which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)			Priority Claimed	
Number	Country	Day Month Year Filed	YES	NO
2003-083687	Japan	25 March, 2003	X	

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States Application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulation, § 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Application Serial No.	Filing Date	Status- patented, pending, abandoned

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below:

PROVISIONAL APPLICATION NUMBER

FILING DATE

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**POWER OF ATTORNEY:** As a named inventor, I hereby appoint the following attorneys, and/or agents with full power of substitution, association, and revocation, to prosecute this application and to transact all business in the Patent and Trademark Office connected herewith.

CUSTOMER NUMBER 23413

I hereby direct that all correspondence and telephone calls in connection with this application be addressed to Customer No. 23413, Cantor Colburn LLP, 55 Griffin Road South, Bloomfield, CT 06002, Telephone No. (860) 286-2929.

I hereby further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application of any patent issued thereon.

<b>Full Name of Sole or First Inventor</b>	<b>Inventor's Signature</b>	<b>Date</b>
Kunihiko IWAMOTO	<i>Kunihiko Iwamoto</i>	27, June, 2005
Residence: Ibaraki, Japan	Citizenship: Japan	
Post Office Address: c/o ROHM Co., Ltd., 21, Saiin Mizosaki-cho, Ukyo-ku, Kyoto 615-8585 Japan		
<b>Full Name of Second Joint Inventor, If Any</b>	<b>Inventor's Signature</b>	<b>Date</b>
Toshihide NABATAME	<i>Toshihide NABATAME</i>	27, June, 2005
Residence: Ibaraki, Japan	Citizenship: Japan	
Post Office Address: c/o Renesas Technology Corp., Intellectual Property Div., 4-1, Marunouchi 2-chome, Chiyoda-ku, Tokyo 100-6334 Japan		
<b>Full Name of Third Joint Inventor, If Any</b>	<b>Inventor's Signature</b>	<b>Date</b>
Koji TOMINAGA		
Residence: , Japan	Citizenship: Japan	
Post Office Address: c/o Horiba, Ltd., 2, Miyano-higashi-cho, Kisshoin, Minami-ku, Kyoto-shi, Kyoto 601-8510 Japan		
<b>Full Name of Fourth Joint Inventor, If Any</b>	<b>Inventor's Signature</b>	<b>Date</b>
Tetsuji YASUDA		
Residence: , Japan	Citizenship: Japan	
Post Office Address: c/o National Institute of Advanced Industrial Science and Technology, Tsukuba Central 4, 1-1, Higashi 1-chome, Tsukuba-shi, Ibaraki 305-8562 Japan		

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<b>Full Name of Sole or First Inventor</b>	<b>Inventor's Signature</b>	<b>Date</b>
Kunihiko IWAMOTO		
Residence: , Japan	Citizenship: Japan	
Post Office Address: c/o ROHM Co., Ltd., 21, Saiin Mizosaki-cho, Ukyo-ku, Kyoto 615-8585 Japan		
<b>Full Name of Second Joint Inventor, If Any</b>	<b>Inventor's Signature</b>	<b>Date</b>
Toshihide NABATAME		
Residence: , Japan	Citizenship: Japan	
Post Office Address: c/o Renesas Technology Corp., Intellectual Property Div., 4-1, Marunouchi 2-chome, Chiyoda-ku, Tokyo 100-6334 Japan		
<b>Full Name of Third Joint Inventor, If Any</b>	<b>Inventor's Signature</b>	<b>Date</b>
Koji TOMINAGA	<i>Koji Tominaga</i>	2005. 6. 17
Residence: Kyoto , Japan	Citizenship: Japan	
Post Office Address: c/o Horiba, Ltd., 2, Miyanohigashi-cho, Kisshoin, Minami-ku, Kyoto-shi, Kyoto 601-8510 Japan		
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Tetsuji YASUDA		
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<b>Full Name of Fourth Joint Inventor, If Any</b>	<b>Inventor's Signature</b>	<b>Date</b>
Tetsuji YASUDA	<i>Tetsuji Yasuda</i>	<i>June 20, 2005</i>
Residence: Ibaraki , Japan	Citizenship: Japan	
Post Office Address: c/o National Institute of Advanced Industrial Science and Technology, Tsukuba Central 4, 1-1, Higashi 1-chome, Tsukuba-shi, Ibaraki 305-8562 Japan		